PCN Number:	20190606001.1	PCN Date:	June 7 2019
Title:	Qualification of additional Fab site (DMOS6) and Assembly site (CDAT) options for the BQ25910YFFR/T		
Customer Contact:	PCN Manager	Dept:	Quality Services
Proposed 1st Ship Date:	Sept 7 2019	Estimated Sample Availability:	Date provided at sample request.

Change Type:					
☒	Assembly Site	☐	Assembly Process	☐	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☐	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☒	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☒	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process
		☐	Part number change		

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of an additional fab (DMOS6) and assembly (CDAT) site for the BQ25910YFFR/T.

Current Fab Site				Additional Fab Site			
Fab Site	Process	Bump Site	Wafer Diameter	Fab Site	Process	Bump Site	Wafer Diameter
RFAB	LBC9	Clark-BP	300 mm	DMOS6	LBC9	CDAT-BP	300 mm

There are no material difference between devices currently manufactured and devices built with this manufacturing option.

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Anticipated impact on Material Declaration

☒	No Impact to the Material Declaration	☐	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI ECO website.

Changes to product identification resulting from this PCN:

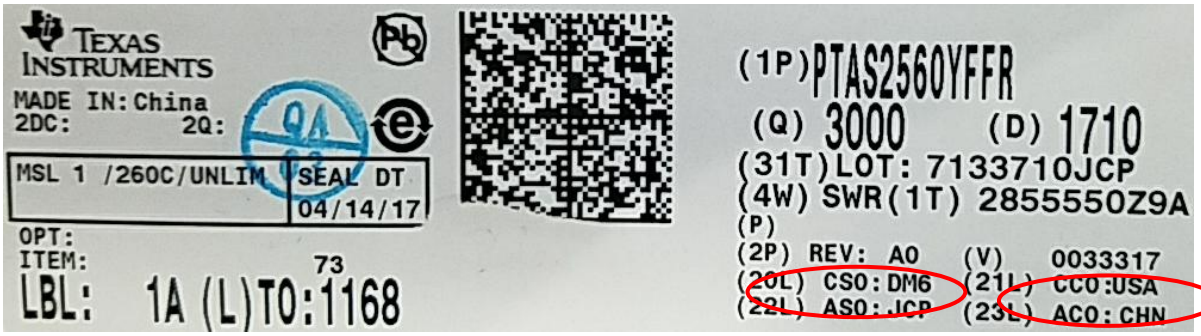
Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
RFAB	RFB	USA	Richardson
DMOS6	**DM6**	**USA**	**Dallas**

Assembly Site Information:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (21L)	Assembly City
TI Clark	QAB	PHL	Angeles City, Pampanga
CDAT	**CDA**	**CHN**	**Chengdu**

Sample product shipping label (not actual product label)



Product Affected:

BQ25910YFFR	BQ25910YFFT

TI Information
Selective Disclosure

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: BQ25910YFF	QBS Product Reference: BQ25910YFF	QBS Product Reference: BQ25970YFF	QBS Product Reference: BQ25970YFFR	QBS Package Reference: BQ25970YFFR	QBS Package Reference: SN2600A0YZF
CLHTOL	Corner Lot Life Test FF, 125C	1000 Hours	-	-	-	-	-	1/45/0
CLHTOL	Corner Lot Life Test FS, 125C	1000 Hours	-	-	-	-	-	1/45/0
CLHTOL	Corner Lot Life Test SF, 125C	1000 Hours	-	-	-	-	-	1/45/0
CLHTOL	Corner Lot Life Test SS, 125C	1000 Hours	-	-	-	-	-	1/45/0
ED	Electrical Characterization	Per Datasheet Parameters	Pass	Pass	-	Pass	Pass	Pass
ELFR	Early Life Failure Rate, 125C	48 Hours	-	-	-	-	-	3/3000/0
ELFR	Early Life Failure Rate, 140C	24 Hours	-	-	1/800/0	-	-	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	3/231/0	3/231/0	-	-	3/231/0
HBM	ESD - HBM	3000 V	1/3/0	-	-	-	-	-
CDM	ESD - CDM	1500 V	1/3/0	1/3/0	-	1/3/0	1/3/0	-
HTOL	Life Test, 125C	1000 Hours	-	-	-	-	-	3/231/0
HTOL	Life Test, 140C	480 Hours	-	3/231/0	3/231/0	-	-	-
HTSL	High Temp. Storage Bake, 150C	1000 Hours	-	-	-	-	-	2/154/0
HTSL	High Temp. Storage Bake ,170C	420 Hours	-	3/231/0	3/231/0	-	-	-
LU	Latch-up	(per JESD78)	2/12/0	1/6/0	-	1/6/0	2/12/0	3/18/0
PD	Physical Dimensions	--	1/5/0	-	-	-	1/5/0	3/60/0
SBS	Bump-shear	--	1/50/0	-	3/150/0	-	1/50/0	3/15/0
SD	Surface Mount Solderability	Pb Free	1/22/0	-	-	-	1/25/0	3/15/0
SD	Surface Mount Solderability	Pb	1/22/0	-	-	-	1/25/0	-
TC	Temperature Cycle, -40 /85C	1039 Cycles	-	-	-	-	-	3/99/0
TC	Temperature Cycle, -55/125C	700 Cycles	-	3/231/0	3/231/0	-	-	3/231/0
UHAST	Unbiased HAST, 130C/85%RH	96 Hours	-	3/231/0	3/231/0	-	-	3/231/0

- QBS: Qual By Similarity
- Qual Device BQ25910YFF is qualified at LEVEL1-260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TBQ25910YFFR
ED	Electrical Characterization	Per Datasheet Parameters	Pass
ELFR	Early Life Failure Rate, 140C	24 Hours	3/2400/0
HAST	Biased HAST, 130C/85%RH	96 Hours	3/231/0
HAST	Unbiased HAST, 130C/85%RH	96 Hours	3/231/0
HBM	ESD - HBM	3000 V	3/9/0
CDM	ESD - CDM	1500 V	3/9/0
HTOL	Life Test, 140C	480 Hours	3/231/0
HTSL	High Temp. Storage Bake, 170C	420 Hours	3/231/0
LU	Latch-up	(per JESD78)	3/18/0
TC	Temperature Cycle, -55/125C	700 Cycles	3/231/0

- Qual Device BQ25910YFFR is qualified at LEVEL 1-260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
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Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

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